

ZABG6002 LOW POWER 6 STAGE FET LNA AND MIXER BIAS CONTROLLER

Summary

The ZABG6002 is a programmable low power depletion mode FET bias and mixer controller intended primarily for satellite Low Noise Blocks (LNBs). Designed to provide system flexibility the ZABG6002 can be programmed to bias six low noise amplifier (LNA) stages or four LNA and two active mixer stages, allowing the ZABG6002 to be used in several system designs.

Combining advanced IC process and packaging techniques, the ZABG6002 operates with minimal current over a wide supply voltage. The small package and reduced component count minimizes the PCB area whilst enhancing overall LNB reliability.

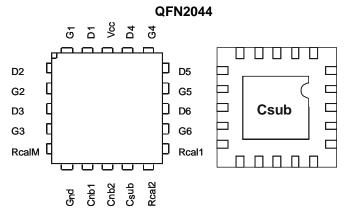
Features

- Six stage FET bias controller, two configurable as mixer stages
- Operating range of 3.0V to 8.0V
- Amplifier FET drain voltages set at 2.0V, mixer drain voltage set at 0.25V
- Amplifier FET drain current selectable from 0 to 15mA, mixer current from 0 to 7.5mA
- Switchable FET's for power management
- FET drain voltages and currents held stable over temperature and V_{CC} variations
- FETs protected against overstress during powerup and power-down.
- Internal negative supply generator allowing single supply operation (available for external use)
- Low quiescent supply current, 1.6mA typical
- · Low external component count

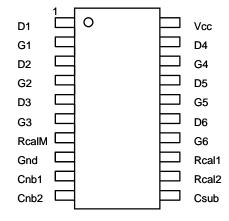
Applications

- Twin LNB's
- Quad LNB's
- US LNB's
- Microwave links
- · PMR and Cellular telephone systems

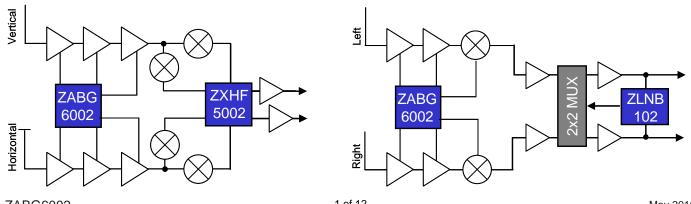
Pin Assignments



QSOP20



Twin LNB System Diagrams







Device Description

The ZABG series of devices are designed to meet the bias requirements of GaAs and HEMT FETs commonly used in satellite receiver LNBs with a minimum of external components whilst operating from a minimal voltage supply and using minimal current.

The ZABG6002 has six FET bias stages that can be user programmed to provide either a two plus four arrangement of amplifier FET stages or a two plus two arrangement of amplifier FET stages along with two active mixer FET stages. Programming of the FET bias stage arrangement and the operating currents of each FET group is achieved by resistors connected to the Rcal1, Rcal2 and RcalM pins, allowing input FETs to be biased for optimum noise, amplifier FETs for optimum gain and mixer FETs (if used) for optimum conversion gain. Amplifier FETs can be operated at currents in the range 0 to 15mA and mixer FETs in the range 0.5 to 7.5mA.

Drain voltages of amplifier stages are set at 2.0V and mixer stages at 0.3V. The drain supplies are current limited to approximately 5% above the operating currents set by their associated Rcal resistors.

As an additional feature the Rcal pins can also be used as logic inputs to disable pairs of FETs as part of a power management scheme or simply an alternative to LNA switching. Driven to a logic high (>3.0V), the inputs disable their associated FET bias stages by switching gate feeds to -2.5V and drain feeds open circuit.

Depletion mode FETs require a negative voltage bias supply when operated in grounded source circuits. The ZABG6002 includes an integrated low noise switched capacitor DC-DC converter generating a regulated output of -2.5V to allow single supply operation. To aid efficiency and 3.3V systems the ZABG6002 has been design to used with supply rails of 3.3V to 8V

It is possible to use less than the devices full complement of FET bias controls, unused drain and gate connections can be left open circuit without affecting operation of the remaining bias circuits.

To protect the external FETs the circuits have been designed to ensure that, under any conditions including power up/down transients, the gate drive from the bias circuits cannot exceed -3V. Additionally each stage has its own individual current limiter. Furthermore if the negative rail experiences a fault condition, such as overload or short circuit, the drain supply to the FETs will shut down avoiding excessive current flow.

The ZABG6002 is available in the 20 pin 4mm x 4mm QFN or QSOP20 package.

Device operating temperature is -40°C to 85°C to suit a wide range of environmental conditions.



ZABG6002

Maximum Ratings

| Parameter | Rating | Unit |
|-----------------------------|-------------|------|
| Supply Voltage | -0.6 to +10 | V |
| Supply Current | 100 | mA |
| Power Dissipation | 600 | mW |
| Operating Temperature Range | -40 to +85 | °C |
| Storage Temperature Range | -40 to 150 | °C |

Electrical Characteristics Measured at $T_{AMB} = 25^{\circ}C$, $V_{CC} = 3.3V$ (Note 1), $R_{CAL1} = R_{CAL2} = 36K$ (setting $I_{D1/2/4/5}$ to 10mA), $R_{CALM} = 68K$ (setting $I_{D3/6}$ to 5mA) unless otherwise stated

| Parameter | Conditions | Symbol | Min. | Тур. | Max. | Unit |
|-------------------------|-----------------------------------|----------------------|------|-------|------|------|
| Operating Voltage Range | | V _{cc} | 3.0 | | 8.0 | V |
| Supply Current | $I_{D1-6} = 0$ | I _{CC} | | 1.6 | 4.0 | mA |
| Supply Current | $I_{D1-6} = 10$ mA, no R_{CALM} | I _{CC(L)} | | 62 | 64 | mΑ |
| Substrate Voltage | $I_{CSUB} = 0$ | V _{CSUB} | -3.0 | -2.65 | -2.0 | V |
| Substrate Voltage | $I_{CSUB} = -200uA$ | V _{CSUB(L)} | | -2.55 | -2.0 | V |
| Oscillator Frequency | | Fosc | 150 | 260 | 600 | kHz |

| Gate Characteristics | | | | | | | | |
|--|---|--------------|------|------|------|----|--|--|
| Gate (G1 to G6, resistor R _{CALM} not present) | | | | | | | | |
| Current Range | ange I _G -100 +500 uA | | | | | | | |
| Voltage Low | $I_D = 12mA, I_G = -10uA$ | $V_{G(L)}$ | -3.0 | -2.5 | -2.0 | V | | |
| Voltage High | $I_D = 8mA, I_G = 0$ | $V_{G(H)}$ | 0 | 0.7 | 1.0 | V | | |
| Voltage Disabled (*1) $I_D = 0$, $I_G = -10uA$, $V_{RCAL1-2} = 3.0V$ $V_{G(DIS)}$ -3.0 -2.5 -2.0 | | | | | | | | |
| Gate (G3 and G6, resistor R _{CALM} prese | ent) | | | | | | | |
| Current Range | | I_{G} | -100 | | +500 | uA | | |
| Voltage Low | $I_D = 6mA, I_G = -10uA$ | $V_{G(L)}$ | -3.0 | -2.5 | -2.0 | V | | |
| Voltage High $I_D = 4mA$, $I_G = 0$ $V_{G(H)}$ 0 0.7 1.0 V | | | | | | | | |
| Voltage Disabled (*1) | $I_D = 0$, $I_G = -10uA$, $V_{RCAL2} = V_{RCALM} 3.0V$ | $V_{G(DIS)}$ | -3.0 | -2.5 | -2.0 | V | | |

| Drain Characteristics | | | | | | | | | |
|--|----------------------------|---------------------|-----|-----|-----|----|--|--|--|
| Drain (D1 to D6, resistor R _{CAL} M not pro- | resent) | | | | | | | | |
| Current Range | | I _D | 0 | | 15 | mA | | | |
| Current Operating Standard Application Circuit I _{D(OP)} 8 10 12 mA | | | | | | | | | |
| Current Disabled (*1) | $V_D = 0, V_{RCAL} = 3.0V$ | I _{D(DIS)} | | | 10 | uA | | | |
| Voltage Operating | $I_D = 10 \text{mA}$ | $V_{D(OP)}$ | 1.8 | 2.0 | 2.2 | V | | | |



ZABG6002

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Electrical Characteristics (Cont.) Measured at $T_{AMB} = 25^{\circ}C$, $V_{CC} = 3.3V$ (Note 1), $R_{CAL1} = R_{CAL2} = 36K$ (setting $I_{D1/2/4/5}$ to 10mA), $R_{CALM} = 68K$ (setting $I_{D3/6}$ to 5mA) unless otherwise stated

| Parameter | Conditions | Symbol | Min. | Тур. | Max. | Unit |
|--|--|----------------------|------|------|------|------|
| Drain Characteristics | | | | | | |
| Drain (D3 and D6, resistor R _{CAL} M pres | ent) | | | | | |
| Current Range | | I _{DM} | 0.5 | | 7.5 | mΑ |
| Current Operating | Standard Application Circuit | I _{DM(OP)} | 4 | 5 | 6 | mA |
| Current Disabled (*1) | $V_D = 0$, $V_{RCAL} = 3.0V$, R_{CALM} not present | I _{DM(DIS)} | | | 10 | uA |
| Voltage Operating | $I_D = 5mA$ | V _{DM(OP)} | 0.25 | 0.3 | 0.35 | V |

| R _{CAL} (1 and 2) | | | | | | |
|----------------------------|-------------------|------------------------|-----|-----|-----|----|
| Disable Threshold (*1) | | V _{RCAL(DIS)} | 1.8 | 2.7 | 3.0 | V |
| Input Current | $V_{RCAL} = 3.0V$ | I _{RCAL(DIS)} | | 1.7 | 10 | uA |

| R _{CALM} | | | | | |
|-------------------------|------------------------|------|------|------|---|
| Disable Threshold (*1) | R _{CALM(DIS)} | 1.5M | 3.3M | 5.0M | Ω |
| R _{CALM} Range | R _{CALM} | 39k | | 390k | Ω |

| Voltage and Temperature dependence (R _{CAL} M not present) | | | | | | | |
|---|--|-----------------------------------|------|--------|--|--|--|
| delta I _D vs V _{CC} | $V_{CC} = 3.3 \text{ to } 8.0 \text{V}$ | dI_D/dV_{CC} | 1.2 | %/V | | | |
| delta I _D vs T _{OP} | $T_{OP} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}$ | dI_D/dT_{OP} | 0.05 | %/°C | | | |
| delta V _D vs V _{CC} | $V_{CC} = 3.3 \text{ to } 8.0 \text{V}$ | dV _D /dV _{CC} | 0.05 | %/V | | | |
| delta V _D vs T _{OP} | $T_{OP} = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ | dV _D /dT _{OP} | 50 | ppm/°C | | | |

| Output Noise | | | | |
|--------------|--|-----------------------|-------|--------|
| | $C_{GATE-GND} = 10nF,$ $C_{DRAIN-GND} = 10nF$ | V _{D(NOISE)} | 0.02 | Vpk-pk |
| Gate Voltage | $C_{GATE-GND} = 10nF,$ $C_{DRAIN-GND} = 10nF$ | V _{G(NOISE)} | 0.005 | Vpk-pk |

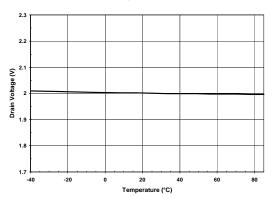
Notes:

- 1. To disable FET stages 3 and 6, pin R_{CAL2} must be set to 3V or above and pin R_{CALM} should be open circuit. See applications section for further information.
- 2. The characteristics are measured using up to three external reference resistors, R_{CAL1}, R_{CAL2} and R_{CALM}, wired from pins R_{CAL1/2/M} to ground. Resistor R_{CAL1} sets the drain current of FETs 1 and 4. If R_{CALM} is not present, resistor R_{CAL2} sets the drain currents of FETs 2, 3, 5 and 6. If R_{CALM} is present, resistor R_{CAL2} sets the drain currents of FETs 2 and 5 and R_{CALM} sets the drain currents of FETs 3 and 6.
- The negative bias voltages are generated on-chip using an internal oscillator. Two external capacitors, C_{NB} and C_{SUB} of value 47nF are required for this purpose.
- 4. The QFN2044 exposed pad must either be connected to Csub or left open circuit.
- 5. Noise voltage measurements are made with FETs and gate and drain capacitors of value 10nF in place. Noise voltages are not measured in production.
- 6. ESD sensitive, handling precautions are recommended.

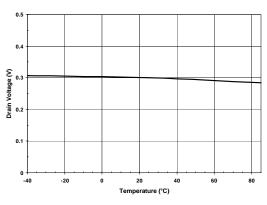


Typical Characteristics Measured at $T_{AMB} = 25^{\circ}C$, $V_{CC} = 3.3V$, $R_{CAL1} = R_{CAL2} = 36K$ (setting I_D to 10mA), $R_{CALM} = 68K$ (setting $I_{D3/6}$ to 5mA) unless otherwise stated

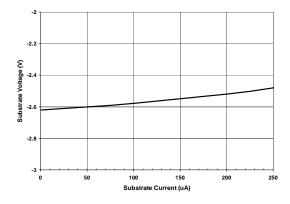
ZABG6002 Drain Voltage (D1 - D6) vs Temperature



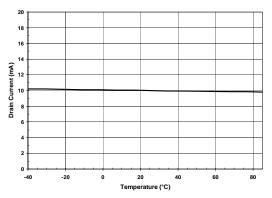
ZABG6002 Drain Voltage (D3 & D6 only) vs Temperature



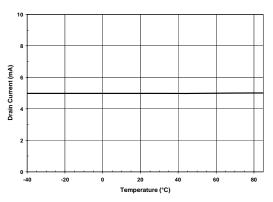
ZABG6002 Substrate Voltage vs Substrate Current



ZABG6002 Drain Current (D1 - D6) vs Temperature



ZABG6002 Drain Current (D3 & D6 only) vs Temperature

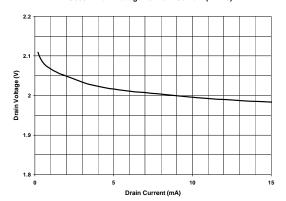




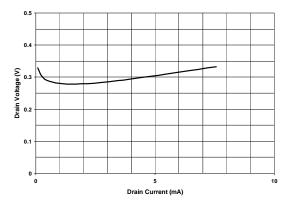
ZABG6002

Typical Characteristics (Cont.) Measured at T_{AMB} = 25°C, V_{CC} = 3.3V, R_{CAL1} = R_{CAL2} = 36K (setting I_D to 10mA), R_{CALM} = 68K (setting I_{D3/6} to 5mA) unless otherwise stated

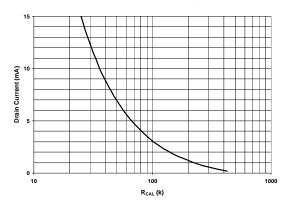
ZABG6002 Drain Voltage vs Drain Current (D1-D6)



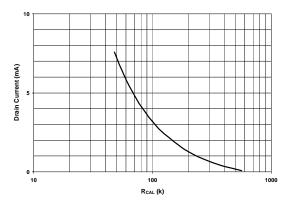
ZABG6002 Drain Voltage vs Drain Current (D3 & D6 only)



ZABG6002 Drain Current vs R_{CAL}



ZABG6002 Drain Current vs R_{CALM}





Application Information

The ZABG6002 is a flexible device and can be set up in a number of ways.

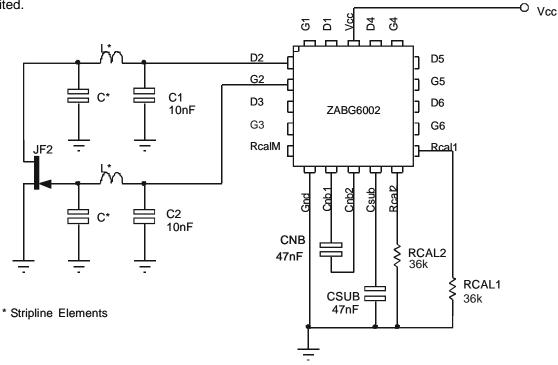
- 1. 6 LNA stages to provide standard bias to the GaAs or HEMT FET's
- 2. 4 LNA stages to provide standard bias to the GaAs or HEMT FET's plus 2 active mixer stages
- 3. Power down FET groups for LNA switching or power saving.

The truth table below shows the function of these features.

| | | | FET Stage | | | | | |
|---|-------|-------------------|-----------|-------------------|--------|-------------------------|--------|--------|
| R _{cal} Pin Resistor Termination | | 1st LNA Stages | | 2nd LNA Stages | | 3rd LNA/Mixer Stages | | |
| Rcal1 | Rcal2 | RcalM | Bias 1 | Bias 4 | Bias 2 | Bias 5 | Bias 3 | Bias 6 |
| Gnd | Gnd | Open | On | On | On | On | On | On |
| Gnd | Gnd | Gnd | On | On | On | On | Mixer | Mixer |
| Gnd | 3V | Open | On | On | Off | Off | Off | Off |
| Gnd | 3V | Gnd | On | On | Off | Off | Mixer | Mixer |
| 3V | Gnd | Open | Off | Off | On | On | On | On |
| 3V | Gnd | Gnd | Off | Off | On | On | Mixer | Mixer |
| 3V | 3V | Open | Off | Off | Off | Off | Off | Off |
| 3V | 3V | Gnd | Off | Off | Off | Off | Mixer | Mixer |

ZABG6002 in 6 LNA mode

Below is a partial applications circuit for the ZABG6002 showing all external components needed for biasing one of the six FET stages available as a normal LNA bias. Each bias stage is provided with a gate and drain pin. The drain pin provides a regulated 2.0V supply that includes a drain current monitor. The drain current taken by the external FET is compared with a user selected level, generating a signal that adjusts the gate voltage of the FET to obtain the required drain current. If for any reason, an attempt is made to draw more than the user set drain current from the drain pin, the drain voltage will be reduced to ensure excess current is not taken. The gate pin drivers are also current limited.



The bias stages are split up into two groups, with the drain current of each group set by an external R_{CAL} resistor. R_{CAL} 1 sets the drain currents of stages 1 and 4, whilst R_{CAL} 2 sets the drain currents of stages 2,3,5 and 6.

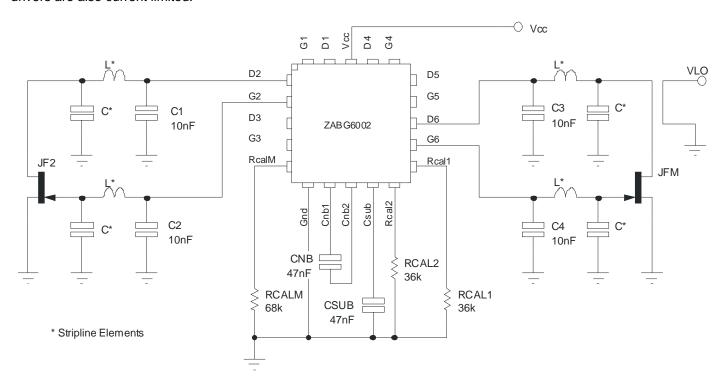




This allows the optimization of drain currents for differing tasks such as input stages where noise can be critical and later amplifier stages where gain may be more important. A graph showing the relationship between the value of R_{CAL} and I_D is provided in the Typical Characteristics section of this datasheet. To ensure that the mixer function is disabled the $R_{CAL}M$ pin should be left open circuit.

ZABG6002 in 4 LNA and 2 active mixer mode

Below is a partial applications circuit for the ZABG6002 showing all external components needed for biasing one of the four FET stages available for LNA bias and one of the two mixer bias stages. Each LNA bias stage is provided with a gate and drain pin. The drain pin provides a regulated 2.0V supply that includes a drain current monitor. Each mixer bias stage is provided with a gate and drain pin. The drain pin provides a regulated 0.3V supply that includes a drain current monitor but optimized to the requirements of an active mixer. The drain current taken by the external FET (LNA and Mixer) is compared with a user selected level, generating a signal that adjusts the gate voltage of the FET to obtain the required drain current. If for any reason, an attempt is made to draw more than the user set drain current from the drain pin, the drain voltage will be reduced to ensure excess current is not taken. The gate pin drivers are also current limited.



The bias stages are split up into three groups, with the drain current of each group set by an external R_{CAL} resistor. R_{CAL} 1 sets the LNA drain currents of stages 1 and 4 and R_{CAL} 2 sets the drain currents of LNA stages 2 and 5. R_{CALM} sets the mixer drain currents of stages 3 and 6. This allows the optimization of drain currents for differing tasks such as input stages where noise can be critical and later amplifier stages where gain may be more important. A graph showing the relationship between the value of R_{CAL} and I_D is provided in the Typical Characteristics section of this datasheet.



General Operation

In both modes the R_{CAL} 1 and R_{CAL} 2 pins can also be used as logic inputs. If set to a logic high state (>3.0V), the associated FET bias stages programmed for LNA use (2V drains) are disabled by driving gate pins to -2,5V and switching drain pins open-circuit. This feature can be used as part of a power management system that turns off any unwanted stages in a multi input receiver.

The ZABG6002 includes a switched capacitor DC-DC converter that is used to generate the negative supply required to bias depletion mode FETs used in common source circuit configuration as shown above. This converter uses two external capacitors, C_{NB} the charge transfer capacitor and C_{SUB} the output reservoir capacitor. The circuit provides a regulated -2.5V supply both for gate driver use and for external use if required (for extra discrete bias stages, mixer bias, local oscillator bias etc.). The -2.5V supply is available from the C_{SUB} pin.

If any bias stages are not required, their gate and drain pins may be left open circuit. If all bias stages associated with an R_{CAL} resistor are not required, then this resistor may be omitted.

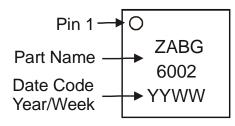
It must be noted that the exposed pad of the QFN package must be either left floating or connected to Csub.

Ordering Information

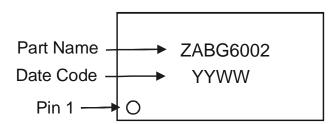
| Device | Package | Reel size (inches) | Tape width (mm) | Quantity per reel |
|----------------|---------|--------------------|-----------------|-------------------|
| ZABG6002JB20TC | QFN2044 | 13 | 12 | 3,000 |
| ZABG6002Q20TC | QSOP20 | 13 | 16 | 2,500 |

Marking Information

QFN2044



QSOP20

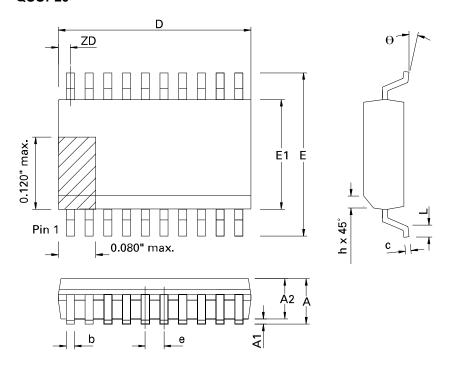






Package Outline Dimensions

QSOP20



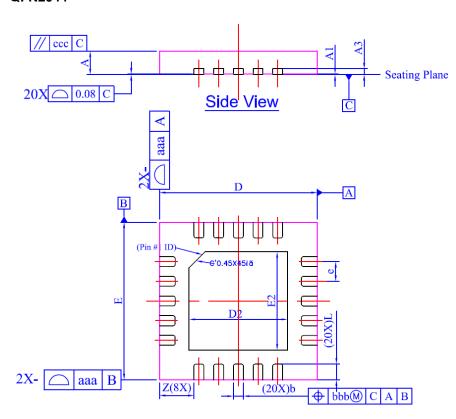
| DIM | Millir | neters | Inches | | |
|-----|--------|--------|--------|-------|--|
| | MIN | MAX | MIN | MAX | |
| А | 1.35 | 1.75 | 0.053 | 0.069 | |
| A1 | 0.10 | 0.25 | 0.004 | 0.010 | |
| A2 | 1.25 | 1.50 | 0.049 | 0.059 | |
| D | 8.56 | 8.74 | 0.337 | 0.344 | |
| ZD | 0.05 | 8 REF | 1.47 | REF | |
| b | 0.20 | 0.30 | 0.008 | 0.012 | |
| С | 0.18 | 0.25 | 0.007 | 0.010 | |
| е | 0.64 | BSC | 0.025 | BSC | |
| E | 5.79 | 6.20 | 0.228 | 0.244 | |
| E1 | 3.81 | 3.99 | 0.150 | 0.157 | |
| Ĺ | 0.41 | 1.27 | 0.016 | 0.050 | |
| θ | 0° | 8° | 0° | 8° | |
| h | 0.25 | 0.50 | 0.010 | 0.020 | |





Package Outline Dimensions (Cont.)

QFN2044



| DIM | Min. | Max. | Тур. |
|-----|------|------|-------|
| D | 3.95 | 4.05 | 4.00 |
| E | 3.95 | 4.05 | 4.00 |
| D2 | 2.40 | 2.60 | 2.50 |
| E2 | 2.40 | 2.60 | 2.50 |
| Α | 0.57 | 0.63 | 0.60 |
| A1 | 0 | 0.05 | 0.02 |
| A3 | | _ | 0.15 |
| b | 0.20 | 0.30 | 0.25 |
| L | 0.35 | 0.45 | 0.40 |
| е | | _ | 0.50 |
| Z | | _ | 0.875 |
| aaa | 0.25 | | |
| bbb | 0.10 | | |
| ccc | 0.10 | | |





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